



Drill Map:

- 0.305mm / 0.0120" (2 holes)
- 0.406mm / 0.0160" (30 holes)
- + 0.800mm / 0.0315" (4 holes)
- ◻ 0.991mm / 0.0390" (4 holes)
- ◊ 1.000mm / 0.0394" (2 holes)
- ⊠ 1.067mm / 0.0420" (9 holes)
- * 1.100mm / 0.0433" (4 holes)
- ⊠ 1.194mm / 0.0470" (4 holes)
- ⊠ 1.295mm / 0.0510" (4 holes)
- ⊕ 2.700mm / 0.1063" (4 holes) (not plated)
- 3.400mm / 0.1339" (4 holes) (not plated)

NOTES:

- 1. Layers: 4
- 2. PCB Thickness: 1.6 mm
- 3. PCB Color: GREEN
- 4. Material Type: FR-4 TG155
- 5. Surface Finish: HASL
- 6. Outer Copper Weight: 1 oz
- 7. Inner Copper Weight: 0.5 oz
- 8. Impedance Control: NO
- 9. Layer Stackup: xxxx
- 10. Via Covering: Plugged
- 11. Min Via Hole Size / Diameter: 0.406 mm / 0.81 mm
- 12. Board Outline Tolerance: +/- 0.2 mm
- 13. Silk Screen: INK-JET/SCREEN PRINTING
- 14. Stencil Framework: YES
- 15. Top+Bottom on single stencil
- 16. Sencil Polishing: Electropolishing
- 17. Fiducials: Etched Through
- 18. Engrave Text

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	62.68 mils
Board overall dimensions:	3937.00 mils x 3110.00 mils		
Min track/spacing:	10.00 mils / 7.73 mils	Min hole diameter:	11.81 mils
Copper Finish:	HAL SnPb	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	White	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Green	3.3	0
F.Cu	copper		1.38 mils		1	0
Dielectric 1	prepreg	Not specified	8 mils	FR4 natural	0	0
In1.Cu	copper		0.6 mils		1	0
Dielectric 2	core	Not specified	41.92913 mils	FR4 natural	0	0
In2.Cu	copper		0.6 mils		1	0
Dielectric 3	prepreg	Not specified	8 mils	FR4 natural	0	0
B.Cu	copper		1.38 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	White	1	0